

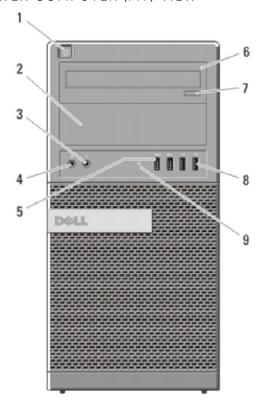
TECHNICAL GUIDEBOOK INSIDE THE OPTIPLEX 7010

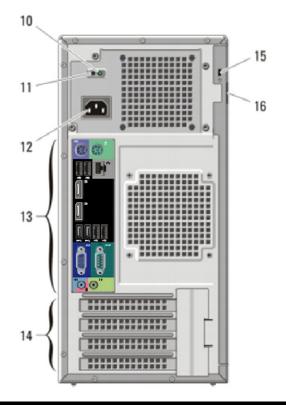


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MINI TOWER COMPUTER (MT) VIEW

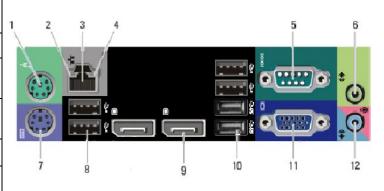


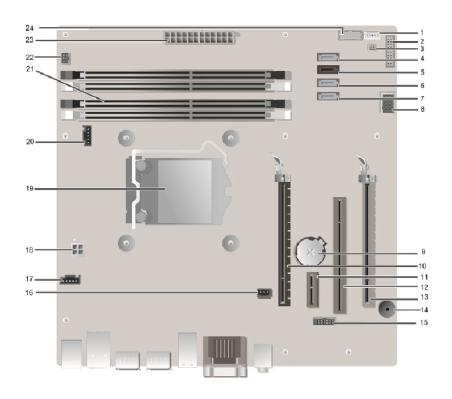


FRO	FRONT VIEW				
1	Power Button, Power Light	6	Optical Drive (optional)		
2	Optical Drive Bay (optional)	7	Optical Drive Eject Button		
3	Headphone Connector	8	USB 2.0 Connectors (2)		
4	Microphone Connector	9	Drive Activity Light		
5	USB 3.0 Connectors (2)				

BAC	CK VIEW		
10	Power Supply Diag- nostic Light	14	Expansion Card Slots (4)
11	Power Supply Diag- nostic Button	15	Kensington / Noble Security Cable Slot
12	Power Connectors	16	Padlock Ring
13	Back Panel Connect- ors		

ВА	BACK PANEL CONNECTORS					
1	PS2 Mouse Con- nector	7	SP2 Keyboard Con- nector			
2	Link Integrity Light	8	USB2.0 Connectors (2)			
3	Network Connector	9	DisplayPort Connector (2)			
4	Network Activity Light	10	USB2.0 Connectors (2) USB3.0 Connectors (2)			
5	Serial Connector	11	VGA Connector			
6	Line-out Connector	12	Line-in/Microphone Connector			

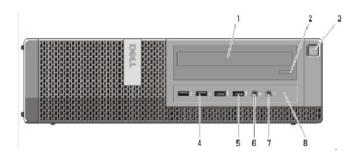


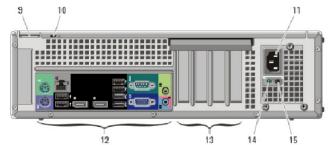


MT System Board Components

Num- ber	Name	Num- ber	Name
1	Internal Speaker Connector (INT_SPKR)	13	PCI-e x16 (wire x4) Connector (SLOT4)
2	Front IO Connector (FRONTPANEL)	14	Buzzer (BEEP)
3	Thermal Sensor Connector (THRM_2)	15	LPC Debug Connector (LPC_DEBUG)
4	SATA 0 Connector (SATA0)	16	Intrusion Switch Connector (INTRUDER)
5	SATA 1 Connector (SATA1)	17	System Fan Connector (FAN_HDD)
6	SATA 2 Connector (SATA2)	18	P2 Power Connector (12V_PWRCONN)
7	SATA 3 Connector (SATA3)	19	Processor Socket (N/A)
8	Internal USB Connector (INT_USB)	20	CPU fan Connector (FAN_CPU)
9	Battery Connector (BATTERY)	21	Memory Connectors (DIMM1, DIMM2, DIMM3, DIMM4)
10	PCI-e x16 Connector (SLOT1)	22	Power Switch Connector (PWR_SW)
11	PCI-e x1 Connector (SLOT2)	23	P1 Power Connector (POWER)
12	PCI Connector (SLOT3)	24	Front USB3.0 Connector (Front _USB)

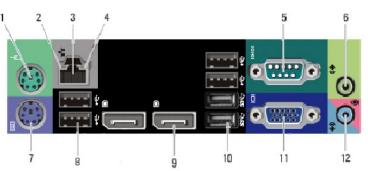
DESKTOP COMPUTER (DT) VIEW

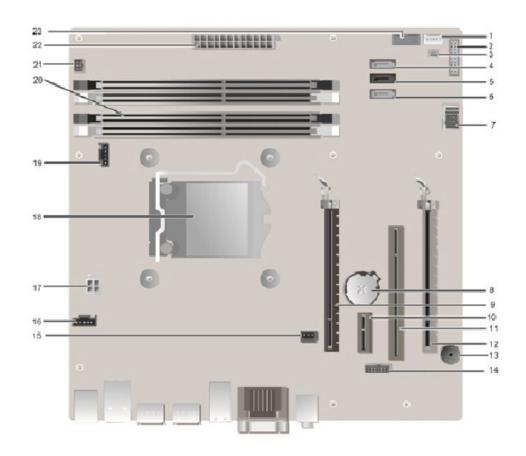




FRC	FRONT VIEW			BACK VIEW			
1	Optical Drive	5	USB 3.0 Connectors (2)	9	Padlock Ring	13	Expansion Card Slots (4)
2	Optical Drive Eject Button	6	Microphone Connector	1 0	Kensington / Noble Security Cable Slot	14	Power Supply Diagnostic Light
3	Power Button, Power Light	7	Headphone Connector	11	Power Connectors	15	Power Supply Diagnostic Button
4	USB 2.0 Connectors (2)	8	Drive Activity Light	1 2	Back Panel Connectors		

BAG	BACK PANEL CONNECTORS				
1	PS2 Mouse Connector	7	PS2 Keyboard Connector		
2	Link Integrity Light	8	USB2.0 Connectors (2)		
3	Network Connector	9	DisplayPort Connector (2)		
4	Network Activity Light	10	USB2.0 Connectors (2) USB3.0 Connectors (2)		
5	Serial Connector	11	VGA Connector		
6	Line-out Connector	12	Line-in/Microphone Connector		

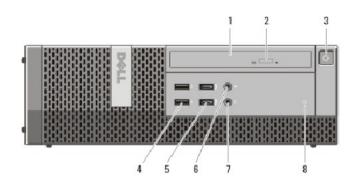


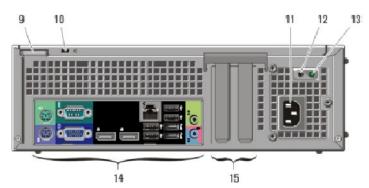


DT System Board Components

Num- ber	Name	Num- ber	Name
1	Internal Speaker Connector (INT_SPKR)	12	PCI-e x16 (wire x4) Connector (SLOT4)
2	Front IO Connector (FRONTPANEL)	13	Buzzer (BEEP)
3	Thermal Sensor Connector (THRM_2)	14	LPC Debug Connector (LPC_DEBUG)
4	SATA 0 Connector (SATA0)	15	Intrusion Switch Connector (INTRUDER)
5	SATA 1 Connector (SATA1)	16	System Fan Connector (FAN_HDD)
6	SATA 2 Connector (SATA2)	17	P2 Power Connector (12V_PWRCONN)
7	Internal USB Connector (INT_USB)	18	Processor Socket (N/A)
8	Battery Connector (BATTERY)	19	CPU fan Connector (FAN_CPU)
9	PCI-e x16 Connector (SLOT1)	20	Memory Connectors (DIMM1, DIMM2, DIMM3, DIMM4)
10	PCI-e x1 Connector (SLOT2)	21	Power Switch Connector (PWR_SW)
11	PCI Connector (SLOT3)	22	P1 Power Connector (POWER)
		23	Front USB3.0 Connector (Front _USB)

SMALL FORM FACTOR COMPUTER (SFF) VIEW

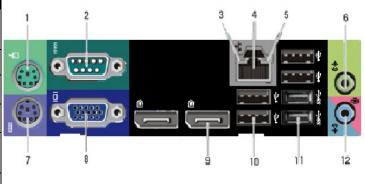


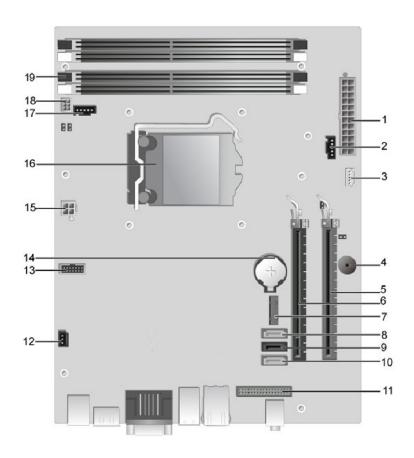


FRO	ONT VIEW		
1	Optical Drive	5	USB 3.0 Connectors (2)
2	Optical Drive Eject Button	6	Microphone Connector
3	Power Button, Power Light	7	Headphone Connector
4	USB 2.0 Connectors (2)	8	Drive Activity Light

BAC	CK VIEW		
9	Padlock Ring	13	Power Supply Diagnostic Light
10	Kensington / Noble Security Cable Slot	14	Back Panel Connectors
11	Power Connectors	15	Expansion Card Slots (2)
12	Power Supply Diagnostic Button		

ВА	BACK PANEL CONNECTORS				
1	PS2 Mouse Connector	7	PS2 Keyboard Connector		
2	Serial Connector	8	VGA Connector		
3	Link Integrity Light	9	DisplayPort Connector(2)		
4	Network Connector	10	USB 2.0 Connectors (2)		
5	Network Activity Light	11	USB2.0 Connectors (2) USB3.0 Connectors (2)		
6	Line-out Connector	12	Line-in/Microphone Connector		

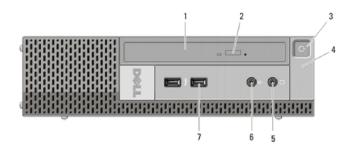


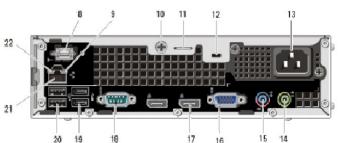


SFF System Board Components

Number	Name	Number	Name
1	P1 power Connector (POWER)	11	Front IO Connector (FRONTPANEL)
2	System fan Connector (FAN_HDD)	12	Intrusion Switch Connector (INTRUDER)
3	Internal Speaker Connector (INT_SPKR)	13	LPC debug Connector (LPC_DEBUG)
4	Buzzer (BEEP)	14	Battery Connector (BATTERY)
5	PCI-e x16 (wire x4) Connector (SLOT2)	15	P2 Power Connector (12V_PWRCONN)
6	PCI-e x16 Connector (SLOT1)	16	Processor Connector (N/A)
7	Front USB3.0 Connector (Front _USB)	17	CPU Fan Connector (FAN_CPU)
8	SATA 2 Connector (SATA2)	18	Power Switch Connector (PWR_SW)
9	SATA 1 Connector (SATA1)	19	Memory Connectors (DIMM1, DIMM2, DIMM3, DIMM4)
10	SATA 0 Connector (SATA0)		

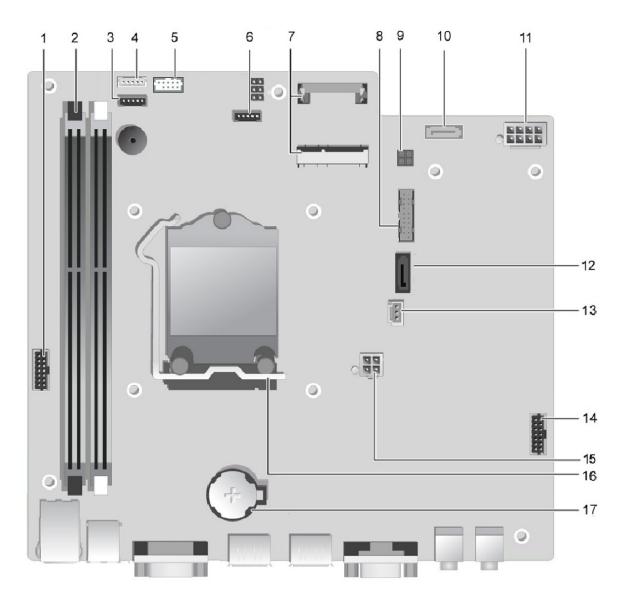
ULTRA SMALL FORM FACTOR COMPUTER (USFF) VIEW





FRO	ONT VIEW		
1	Optical Drive	5	Headphone Connector
2	Optical Drive Eject Button	6	Microphone Connector
3	Power Button, Power Light	7	USB 3.0 Connectors (2)
4	Drive Activity Light		

BAC	K VIEW		
8	Wi-Fi Antenna (optional)	15	Line-in/ Microphone Connector
9	Network Activity Light	16	VGA Connector
10	Captive Thumbscrew	17	DisplayPort Connector (2)
11	Padlock Ring	18	Serial Connector
12	Kensington / Noble Security Cable Slot	19	USB 3.0 Connectors (2)
13	Power Connector	20	USB 2.0 Connectors (2)
14	Line-Out Connector	21	Network Connector
		22	Link Integrity Light



USFF System Board Components

Number	Name	Number	Name
1	Front Panel Connector (FRONTPANEL)	9	HDD-ODD Power Connector (HDD_ODD_POWER)
2	Memory Connector (DIMM_1,DIMM_2)	10	SATA 1 Connector (SATA1)
3	CPU Fan Connector (FAN_CPU)	11	P1 Power Connector (POWER)
4	Internal Speaker Connector (INT_SPKR)	12	SATA 0 Connector (SATA0)
5	Front IO Connector (F_USB_AUDIO)	13	Intrusion Switch Connector (INTRUDER)
6	System Fan Connector (FAN_HDD)	14	LPC Debug Connector (LPC_DEBUG)
7	Mini-PCI Socket (PCIE_MINICARD)	15	P2 Power Connector (12V_PWRCONN)
8	Front USB3.0 connector (Front USB)	16	Processor socket (N/A)
		17	Battery Connector (BATTERY)

MARKETING SYSTEM CONFIGURATIONS

NOTE: Offerings may vary by country. For more information regarding the configuration of your computer, click Start>Help and Support and select the option to view information about your computer.

OPERATING SYSTEM

	MT DT SFF USFF					
Windows Operating System	Microsoft® Windows 7® Home Basic SP1 (32 and 64 bit), Microsoft® Windows 7® Home Premium SP1 (32 and 64 bit), Microsoft® Windows 7® Home Premium w/MUI SP1 (32 and 64 bit), Microsoft® Windows 7® Professional w/MUI SP1 (32 and 64 bit), Microsoft® Windows 7® Professional SP1 (32 and 64 bit), Microsoft® Windows 7® Ultimate SPI (32 and 64 bit),					
Other	Ubuntu (N-Series DIB) (32bit) Ubuntu (32bit)					
OS Media Support	Optional					

CHIPSET

	МТ	DT	SFF	USFF		
Chipset	Intel Q77 Express Chipset					
Non-volatile memory on chipset						
BIOS Configuration SPI (Serial Peripheral Interface)	64Mbit (8MB) &32Mbit(4MB) lc	ocated at SPI_FLAS	SH on chipset		
TPM 1.2 Security Device (Trusted Platform Module) ¹		4KB located at T	PM1.2 on chipset			
Non-TPM	Available in select countries					
NIC EEPROM	LOM configuration contained within SPI_FLASH – no dedicated LOM EEPROM					

PROCESSOR¹

NOTE: Global Standard Products (GSP) are a subset of Dell's relationship products that are managed for availability and synchronized transitions on a worldwide basis. They ensure the same platform is available for purchase globally. This allows customers to reduce the number of configurations managed on a worldwide basis, thereby reducing their costs. They also enable companies to implement global IT standards by locking in specific product configurations worldwide. The following GSP processors identified below will be made available to Dell customers.

NOTE: Processor numbers are not a measure of performance. Processor availability subject to change and may vary by region/country.

	MT	DT	SFF	USFF
Intel® Quad Core Processors				
Intel® Core™ i7 3770 / 3.10GHz, 8M, VT-x, VT-d, TXT (vPro™), 77W	GSP	GSP	GSP	
Intel® Core™ i7 3770S / 3.40GHz, 8M, VT-x, VT-d, TXT (vPro™), 65W				GSP
Intel® Core™ i5 3570 / 3.40GHz, 6M, VT-x, VT-d, TXT (vPro™), 77W ²	GSP	GSP	GSP	
Intel® Core™ i5 3570S / 3.10GHz, 6M, VT-x, VT-d, TXT (vPro™), 65W ²				GSP
Intel® Core™ i5 3470 / 3.20GHz, 6M, VT-x, VT-d, TXT (vPro™), 77W ²	GSP	GSP	GSP	
Intel® Core™ i5 3475S / 2.90GHz, 6M, VT-x, VT-d, TXT (vPro™), 65W ²	GSP	GSP	GSP	GSP
Intel® Core™ i5 3470S / 2.90GHz, 6M, VT-x, VT-d, TXT (vPro™), 65W ²				GSP
Intel® Core TM i5 3550 / 3.30GHz, 6M, VT-x, VT-d, TXT (vPro TM), 77W 3	Х	Х	Х	
Intel® Core TM i5 3550S / 3.00GHz, 6M, VT-x, VT-d, TXT (vPro TM), $65W^3$				Х
Intel® Core™ i5 3450 / 3.10GHz, 6M, 77W ³	Х	Х	Х	
Intel® Core™ i5 3450S / 2.80GHz, 6M, 65W ³				Х
Intel® Dual Core Processors				
Intel® Core™ i3 2130 / 3.40GHz, 3M, VT-x, 65W	Х	Х	Х	Х
Intel® Core™ i3 2125 / 3.30GHz, 3M, VT-x, 65W	Х	Х	Х	Х
Intel® Core™ i3 2120 / 3.30GHz, 3M, VT-x, 65W	Х	Х	Х	Х
Intel® Core™ G860 / 3.0GHz, 3M, VT-x, 65W ²	Х	Х	Х	Х
Intel® Core™ G850 / 2.9GHz, 3M, VT-x, 65W ³	Х	Х	Х	Х
Intel® Core™ G640 / 2.8GHz, 3M, VT-x, 65W ²	Х	Х	Х	Х
Intel® Core™ G630 / 2.7GHz, 3M, VT-x, 65W ³	Х	Х	Х	Х
Intel® Celeron Processors				
Intel® Core™ G540 / 2.5GHz, 2M, VT-x, 65W ²	Х	Х	Х	Х
Intel® Core™ G530 / 2.5GHz, 2M, VT-x, 65W ³	Х	Х	Х	Х
Intel® Core™ G460 / 1.8GHz, 1.5M, VT-x, 35W	Х	Х	Х	Х

¹ 3rd generation CPUs natively support 3 displays with the integrated CPU graphics. Three simultaneous display output requires one DP port with a maximum resolution of 2500x1600 at 60Hz refresh rate and a DP and VGA port with max resolutions of 1920x1200 at 60Hz refresh rates.

² Post launch CPU, available from June for G860, G540; July for G640, i5 3470/S, i5 3570/S, i5 3475S.

³ Available at launch, will be replaced in June or July, i5 3470/S replace i5 3450/S; i5 3570/S replace i5 3550/S; G860 replace G850; G640 replace G630; G540 replace G530.

MEMORY

NOTE: Memory modules should be installed in pairs of matched memory size, speed, and technology. If the memory modules are not installed in matched pairs, the computer will continue to operate, but with a slight reduction in performance. The entire 16GB memory range is available to 64-bit operating systems.

	MT	DT	SFF	USFF
Type: DDR3 Synch DRAM Non-ECC Memory		1600)MHz ²	
DIMM Slots	4	4	4	2
DIMM Capacities	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB
Minimum Memory	2GB	2GB	2GB	2GB
Maximum System Memory	16GB ¹	16GB ¹	16GB ¹	16GB ¹
Memory configurations				
16GB ¹ DDR3, 1600MHz ² , (4 x 4GB)	Х	Х	Х	
16GB ¹ DDR3, 1600MHz ² , (2 x 8GB)				Х
8GB ¹ DDR3, 1600 MHz ² , (2 x 4GB)	Х	Х	Х	Х
6GB ¹ DDR3, 1600MHz ² , (2GB + 4GB)	Х	Х	Х	Х
4GB ¹ DDR3, 1600 MHz ² , (2 x 2GB)	Х	Х	Х	Х
4GB ¹ DDR3, 1600MHz ² , (1 DIMM)	Х	Х	Х	Х
2GB DDR3, 1600MHz ² , (1 DIMM)	Х	Х	Х	Х

¹To fully utilize 4GB or more of memory requires a 64-bit enabled processor and 64-bit operating system. With 32-bit OS, the total amount of available memory will be less than 4GB. The amount less depends on the actual system configuration.

² 1600MHz memory will only perform as 1600MHz memory when 3rd generation CPUs are used. It will perform as 1333MHz memory if 2nd generation i3 2130, i3 2125, i3 2120, G860, G850 CPUs are installed in the system. It will perform as 1066MHz memory if 2nd generation G640, G630, G540, G530, G460 CPUs are installed in the system.

DRIVES AND REMOVABLE STORAGE

	МТ	DT	SFF	USFF
Bays:				
5.25-inch Optical Bay Supported (External)	2	1	1	1
Optical Drives Supported (maximum)	2	1	1 (slim-line)	1 (slim-line)
Hard Drive Bay Supported (Internal)	2	1	1	1
Hard Drives Supported 3.5"/2.5" (maximum)	2/2	1/2	1/2	0/1
Interface:	·			
SATA 2.0	2	1	1	0
SATA 3.0	2	2	2	2
3.5" Hard Drives:				
1TB ¹ SATA 7200 RPM HDD	Х	Х	Х	
500GB ¹ SATA 7200 RPM HDD	Х	Х	Х	
250GB ¹ SATA 7200 RPM HDD	Х	Х	Х	
2.5" Hard Drives:				
500GB ¹ SATA 7200 RPM HDD	Х	Х	Х	Х
320GB ¹ SATA 7200 RPM HDD	Х	Х	Х	Х
320GB ¹ SATA 7200 RPM OPAL SED w/FIPS HDD	Х	Х	Х	Х
500GB ¹ SATA 7200 RPM Hybrid HDD	Х	Х	Х	Х
128GB ¹ SATA Solid State drive	X	Х	Х	Х
Optical Drive: (SFF/USFF require slim-line optical drive)				
DVD+/-RW ² SATA	Х	Х	Х	Х
DVD-ROM ³ SATA	Х	Х	Х	Х
Media Card Reader:				
Dell 19 in 1 Media Card Reader ⁴	Х	Х		

¹ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

² Discs burned with this drive may not be compatible with some existing drives and players; using DVD+R media provides maximum compatibility.

³ DVD-ROM drives may have write-capable hardware that has been disabled via firmware modifications.

⁴ Dell 19 in 1 Media Card Reader (MCR) is supported via a F5 to F3 bay converter on the MT and DT and requires a slim line optical drive.

SYSTEM BOARD CONNECTORS

NOTE: See Detailed Engineering Specifications for maximum card dimensions.

	MT	DT	SFF	USFF
PCI Slot(s) ¹	1	1		
PCIe x16 Slot(s) ²	1	1	1	
PCIe x16 (wired x4)Slot(s) ³	1	1	1	
PCIe x1 Slot(s) ³	1	1		
miniPCle connector(s) ³				1
Serial ATA (SATA) ⁴	4	3	3	2

¹PCI Slots (Support Standard Rev 2.3)

² PCIe x16 Slots (Support Standard Rev 3.0)

³ PCIe x16 (wired x 4), PCIe x1 Slots, miniPCIe (Support Standard Rev 2.0)

⁴ Serial ATA (2 ports Support Standard Rev 3.0, the rest of ports Support Standard Rev 2.0)

GRAPHICS/VIDEO CONTROLLER

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	МТ	DT	SFF	USFF
Integrated Intel® HD Graphics 2500/4000 (3 rd generation Core i3/i5/i7 CPUs); Integrated Intel® HD Graphics 2000/3000 (2 nd generation Core i3 CPUs); Integrated Intel® HD Graphics (Pentium® Dual Core / Celeron® CPU);	Integrated on CPU			
Enhanced Graphic/Video Options				
1GB AMD RADEON HD 7570		Optional card		
1GB AMD RADEON HD 7470		Optional card		

EXTERNAL PORTS/CONNECTORS

	MT	DT	SFF	USFF	
USB 2.0 (Front/Rear/Internal)	2/4/2	2/4/2	2/4/0	0/2/0	
USB 3.0 (Front/Rear/Internal)	2/2/0	2/2/0	2/2/0	2/2/0	
Serial		1 R	ear		
Network Connector (RJ-45)		1 R	ear		
PS/2	2 Rear				
1394 Controller via optional PCI card	Optional FH Optional LP card card				
Video:					
VGA		1 Re	ear		
DisplayPort		2 R	ear		
Audio:					
Line in for microphone	1 Front				
Line in for microphone or stereo	1 Rear				
Line out for headphones or speakers		1 Front	, 1 Rear		

COMMUNICATIONS - NETWORK ADAPTER (NIC)

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	MT	DT	SFF	USFF
Intel® 82579LM Gigabit ¹ Ethernet LAN 10/100/1000 (Remote Wake Up, PXE support and Intel Active Management Technology support)		Integrated on sy	stem board	
Broadcom NetXtreme 10/100/1000 PCIe Gigabit Networking Card		Optional card		

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - WIRELESS

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	MT	DT	SFF	USFF
Dell Wireless 1530 PCIe WLAN card (802.11n)	Optional card			
Dell Wireless 1530 half miniPCIe WLAN card (802.11n)			Optional	

AUDIO AND SPEAKERS

	MT	DT	SFF	USFF
Realtek ALC269Q High Definition Audio Codec	Integrated on system board			
Dell AX210 USB Stereo speakers	Optional			
Dell AX510/AX510PA Flat Panel Soundbar Speakers	Optional			

KEYBOARD AND MOUSE

	МТ	DT	SFF	USFF		
Dell USB Entry Keyboard with optional palmrest		Optional				
Dell Multimedia Pro Keyboard		Optional				
Dell Smart Card Keyboard		Optional				
Dell USB Optical Mouse		Optional				
Dell Laser Mouse		Optional				

SECURITY

	MT	DT	SFF	USFF		
Trusted Platform Module (TPM) 1.2 ¹	Integrated on system board					
Chassis Intrusion Switch	Optional					
Dell Smartcard Keyboard	Optional					
Chassis lock slot and loop support	Standard					
Dell Data Protection Hardware Encryption Engine	Optional					

¹TPM is not available in all countries. Depending on your country regulations, no-TPM system boards may be available.

SOFTWARE

	MT	DT	SFF	USFF	
Dell Client Manager	Available via Dell.com				
Dell Data Protection Access (DDPA)	Standard				
Dell Data Protection Encryption (DDPE)	Optional				

ENVIRONMENTAL

NOTE: For more details on Dell Environmental features, please to go to Environmental Attributes section. See your specific region for availability.

	MT	DT	SFF	USFF	
Sustainable packaging	Х	Х	Х		
MultiPack packaging	Optional, US only				
Energy Efficient Power Supply	Optional			Standard	

ALL-IN-ONE STANDS AND MOUNTS

	MT	DT	SFF	USFF
Small Form Factor AIO Stand			Optional	
Ultra Small Form Factor AIO Stand				Optional
Ultra Small Form Factor Wall Mount / Desk Mount				Optional

SERVICE AND SUPPORT

NOTE: For more details on Dell Service Plans please to go to: www.dell.com/service/service_plans

	MT	DT	SFF	USFF
3 Year Warranty ¹ Next Business Day On-site ² (3-3-3)	Standard			
ProSupport	Optional			

¹ For a copy of our guarantees or limited warranties, please write Dell USA L.P., Attn: Warranties, One Dell Way, Round Rock, TX 78682. For more information, visit www.dell.com/warranty.

² Service may be provided by third-party. Technician will be dispatched if necessary following phone-based troubleshooting. Subject to parts availability, geographical restrictions and terms of service contract. Service timing dependent upon time of day call placed to Dell. U.S. only.

DETAILED ENGINEERING SPECIFICATIONS

SYSTEM DIMENSIONS (PHYSICAL)

NOTE: System Weight and Shipping Weight is based on a typical configuration and may vary based on PC configuration. A typical configuration includes: integrated graphics, one hard drive, one optical drive.

	МТ	DT	SFF	USFF
	1411	וט	355	USFF
Chassis Volume (liters)	26.27	15.06	8.38	3.70
Chassis Weight (pounds/kilograms)	20.68 / 9.4	17.38 / 7.9	13.2 / 6.0	7.26 / 3.3
Chassis Dimensions: (HxWxD)				
Height (inches/centimeters)	14.17 / 36	14.17 / 36	11.42 / 29	9.32 / 23.67
Width (inches/centimeters)	6.89 / 17.5	4.02 / 10.2	3.65 / 9.26	2.56 / 6.5
Depth (inches/centimeters)	16.42 / 41.7	16.14 / 41	12.28/31.2	9.44 / 24
Shipping Weight (pounds/kilograms - includes packaging materials)	24.57 / 11.17	20.75 / 9.43	15.82/7.19	9.63 /4.375
Packaging Parameters (HxWxD)				
Height (inches/centimeters)	21.31/54.13	21.31 / 54.13	19.25/48.90	19.13/48.59
Width (inches/centimeters)	18.75/47.63	18.75/47.63	15.81/40.16	14.38/36.53
Depth (inches/centimeters)	14.09 / 35.79	10.84/27.53	10.19/25.88	9.63/24.46

SYSTEM BOARD CONNECTOR MAXIMUM ALLOWABLE DIMENSIONS

	МТ	DT	SFF	USFF
PCI Slot (Voltage supported 3.3V/5V/12V/-12V)	1	1		
Height (inches/centimeters)	4.376 / 11.115	2.731 /6.89		
Length (inches/centimeters)	6.6 / 16.765	6.6/16.765		
Maximum Wattage	25W	25W		
PCIex16 Slot (BLUE) (Voltage supported 3.3V/12V)	1	1	1	
Height (inches/centimeters)	4.376 / 11.115	2.731 /6.89	2.731 /6.89	
Length (inches/centimeters)	6.6/ 16.765	6.6 /16.765	6.6 /16.765	
Maximum Wattage	75W	50W	50W	
PClex16 wired as x4 Slot (BLACK) (Voltage supported 3.3/12V)	1	1	1	
Height (inches/centimeters)	4.376 / 11.115	2.731 /6.89	2.731 /6.89	
Length (inches/centimeters)	6.6 / 16.765	6.6 /16.765	6.6/16.765	
Maximum Wattage	25W	25W	25W	
PCIe x1 Slot (Voltage supported 3.3V/12V)	1	1		
Height (inches/centimeters)	4.376 / 11.115	2.731 / 6.89		
Length (inches/centimeters)	4.5 / 11.44	4.5 / 11.44		
Maximum Wattage	10W	10W		
Mini PCle x1 Slot				1

SYSTEM LEVEL ENVIRONMENTAL AND OPERATING CONDITIONS

	MT	DT	SFF	USFF	
Temperature					
Operating		10°C to 35°C	(50°F to 95°I	F)	
Non-Operating (Storage)	-	40°C to 65°C	(-40°F to 149	9°F)	
Relative Humidity		20% to 80% (n	on-condensi	ng)	
Maximum vibration					
Operating	0.25	G at 3 to 200	Hz at 0.5 octa	ave/min	
Non-Operating	0.5	G at 3 to 200	Hz at 1 octav	e/min	
Maximum Shock					
Operating		nalf-sine pulse of 50.8 cm/sec			
Non-Operating	27-G faired square wave with a velocity change of 508 cm/sec (200 inches/sec)				
Maximum Altitude					
Operating	-15.2 to 3048 m (-50 to 10,000 ft)				
Non-Operating	-15	-15.2 to 10,668 m (-50 to 35,000 ft)			

POWER

NOTE: These form factors utilize a more efficient Active Power Factor Correction (APFC) power supply. Dell recommends only Universal Power Supplies (UPS) based on Sine Wave output for APFC PSUs, not an approximation of a Sine Wave, Square Wave, or quasi-Square Wave. If you have questions, please contact the manufac-

	M	T	DT		SFF		USFF
	APFC	EPA	APFC	EPA	APFC	EPA	EPA
Power Supply Wattage	275W	275W High Efficiency	250W	250W High Efficiency	240W	240W High Efficiency	200W High Efficiency
AC input Voltage Range	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac
AC input current (low ac range/high AC range)	5.0A / 2.5A	5.0A / 2.5A	4.4A / 2.2A	4.4A / 2.2A	4.0A / 2.0A	3.6A / 1.8A	2.9A / 1.45A
AC input Frequency	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47 – 63 Hz
AC holdup time (80% load)	16 mini sec	16 mini sec	16 mini sec	16 mini sec	16 mini sec	16 mini sec	16 mini sec
Minimum Efficiency (Energy Star 5.2 Compliant)		87 – 90 – 87% @ 20 – 50 – 100% load		87 – 90 – 87% @ 20 – 50 – 100% load		87 - 90 - 87% @ 20 - 50 - 100% load	87 – 90 – 87% @ 20 – 50 – 100% load
Typical Efficiency (Active PFC)	65%		65%		65%		N/A
DC parameters							
+3.3V output	10.0A	10.0A	7.0 A	7.0 A	3.5A	3.5A	N/A
+5.0V output	13A	13A	15A	15A	11A	11A	N/A
+12.0V output	12VA/17A; 12VB/10A	12VA/17A; 12VB/10A	17.8A	17.8A	17A	17A	+12VA - 12.5 A & +12VB - 6.0 A Note: +12VB Rated at 0.4A when in Standby Mode.
+5.0V auxiliary output	4.0A	4.0A	4.0	4.0	4.0A	4.0A	N/A
-12.0V output	0.5A	0.5A	0.5A	0.5A	0.5A	0.5A	0.1 A
Max total power	275W	275W	250W	250W	240W	240W	200W
Max combined +3.3V / +5.0V power	100W	100W	90W	90W	60W	60W	N/A
Max combined 12.0V power (note: only if more than one 12V rail)	240W	240W	N/A	N/A	N/A	N/A	200W
BTUs/h (based on PSU max wattage)	938 BTU	938 BTU	853 BTU	853 BTU	819 BTU	819 BTU	682 BTU
Power Supply Fan	80*25mm	80*25mm	80*20/25m m	80*20/25m m	60*25mm	60*25mm	N/A
Compliance:							
Erp Lot6 Tier 2 0.5watt requirement	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Blue Angel Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Climate Savers / 80Plus Compliant	No	Yes	No	Yes	No	Yes	Yes
FEMP Standby Power Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes
CECP Compliant	No	Yes	No	Yes	No	Yes	Yes

POWER

NOTE: These form factors utilize a more efficient Active Power Factor Correction (APFC) power supply. Dell recommends only Uninterruptible Power Supplies (UPS) based on Sine Wave output for APFC PSUs, not an approximation of a Sine Wave, Square Wave, or quasi-Square Wave. If you have questions, please contact the manufacture to confirm the output type.

3.0v CMOS battery	(Type and estimat	ed battery lif	fe)	
Brand	Туре	Voltage	Composition	Life
PANASONIC	CR-2032L/ BE	3V	Lithium	Continuous Discharge Under 15 k Ω Load to 2.5V End-Voltage. 20°C \pm 2°C: 1183Hrs. or Longer, 1133Hrs.or Longer after 12 months.
MITSUBISHI	CR2032	3V	Lithium	Continuous Discharge Under 15 k Ω Load to 2.0V End-Voltage. 20°C±2°C: 1000Hrs. or Longer, 970Hrs.or Longer after 12 months. 0°C±2°C: 910Hrs. or Longer, 890Hrs.or Longer after 12 months.

AUDIO

INTEGRATED REALTEK ALC269Q HIGH DEFINITION AUDIO	MT	DT	SFF	USFF	
High Definition Stereo support	Х	Х	Х	Х	
Number of channels	2				
Number of Bits / Audio resolution		16, 20, and 24	4-bit resolutio	on	
Sampling rate (recording/playback)	Support	44.1K/48K/96	5K/192 kHz sa	mple rates	
Signal to Noise Ratio	98 dB	DAC outputs,	90 dB for AD	C inputs	
Analog Audio	Х	Х	Х	Х	
Dolby Digital					
THX					
Digital out (S/PDIF)					
Audio Jack Impedance					
Microphone		40K ohm	n∼60K ohm		
Line-In		40K ohm~60K ohm			
Line-Out	100~150 ohm				
Headphone	1~4 ohm				
Internal Speaker Power Rating		2Watt (peak) /	1Watt (avera	ge)	

COMMUNICATIONS - INTEGRATED LAN

INTEGRATED INTEL® 82579 GIGABIT ¹ ETHERNET LAN 10/100/1000	МТ	DT	SFF	USFF	
External Connector Type	RJ45				
Data Rates supported		10/100/1	L000 Mbps		
Controller Details					
Controller bus architecture	PCle-bas		or S0 state, SMBu wer state	s for Sx	
Integrated memory	N/A				
Data transfer mode (example Bus-Master DMA)	N/A				
Power consumption (full operation per data rate connection speed)		711mV	V (Max.)		
Power consumption (standby operation)		227m\	W (Max.)		
IEEE standards compliance (example 802.1P)	802.3				
Hardware Certifications (example FCC, B, GS mark)	N/A				
Boot ROM Support	EEPROM (located in SPI)				
Network Transfer Mode (example Full Duplex, Half Duplex)					
Network Transfer Rate (example 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	10 Mb (full/half-duplex) 100 Mb (full/half-duplex) 1000 Mb (full-duplex)				

COMMUNICATIONS - INTEGRATED LAN (CONT.)

INTEGRATED INTEL® 82579 GIGABIT ¹ ETHERNET LAN 10/100/1000 (CONT.)	МТ	DT	SFF	USFF		
Environmental	ental					
Operating temperature	0°C to 85°C (32° F to 185° F)					
Operating humidity	20% to 80% (non-condensing)					
Operating System Driver Support	Windows 7 32/64, Windows XP 32/64, Vista 32/64					
Manageability (examples WOL, PXE)	WOL, PXE 2.1					
Management Capabilities Alerting	Intel® Standard Manageability, 3rd generation i5/i7 processors with vPro Technology					

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - NETWORK ADAPTER (NIC)

BROADCOM NETXTREME 10/100/1000 PCIE GIGABIT¹ NETWORKING CARD	МТ	DT	SFF	USFF		
Connector Type	RJ45					
Data Rates supported	10/	10/100/1000 Mbps Half/Full duplex				
Controller Details						
Controller bus architecture (example PCIe 1.0a x1)		PCle o	c1.0a x1			
Integrated memory		64KBytes R	X, 8KBytes TX			
Data transfer mode (example Bus-Master DMA)		Bus-Master DMA				
Power consumption (full operation per data rate connection speed)		2.84W (860mA @ +3.3V)				
Power consumption (standby operation)		Less tha	n 300mW			
IEEE standards compliance (example 802.1P)		802.3, 802.2,	802.3x, 802.1	Lp		
Hardware Certifications (example FCC, B, GS mark)		FCC B, V	CCI B, CE			
Boot ROM Support		١	No			
Network Transfer Mode (example Full Duplex, Half Duplex)						
Network Transfer Rate (example 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	100BA 100BA 1000BA	s Max* ops Max* opsMax* bps Max* nment.				

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - NETWORK ADAPTER (NIC) (CONT.)

BROADCOM NETXTREME 10/100/1000 PCIE GIGABIT¹ NETWORKING CARD (CONT.)	МТ	DT	SFF	USFF	
Environmental					
Operating temperature	0°C C to 55°C (32°F - 131°F)				
Operating humidity	5% ~ 85% (non-condensing)				
Operating System Driver Support	Microsoft Client XP/Vista/Win 7 (32bit/64bit) Linux				
Manageability (examples WOL, PXE)	WOL, PXE2.1, ACPI				
Management Capabilities Alerting (example ASF 2.0)	None				

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

1394a FIREWIRE PCI ADD-IN CARD	
Connector Type	IEEE-1394a-2000 (6 pins)
Controller Details	
Controller bus architecture (example PCIe 1.0a x1)	PCI 2.3
Chipset	LSI
IO Ports	IEEE 1394 (FireWire) with a transfer rate of up to 400Mbps
Power Consumption	Under 30 mA
Connector	2 IEEE-1394a 6 pins connectors
OS Support	Microsoft Client XP/Vista/Win 7 (32bit/64bit)

COMMUNICATIONS - WIRELESS

DELL WIRELESS 1530 PCIE WLAN CARD (802.11N)	MT	DT	SFF	USFF	
Dell Wireless 1530 PCIe WLAN card (802.11n)	Integrated Antenna				
Dell Wireless 1530 half miniPCIe WLAN card (802.11n)		C		Custom WLAN Antenna	
Controller Details					
Controller bus architecture	Electrically co		e PCI Express I and PCIe v1.0a	Base Specification	
WLAN standards supported		802.11a, 802.11b	, 802.11g, 802	.11n	
802.11b Data Rates supported	11, 5.5, 2, 1 Mbps				
802.11a Data Rates supported	54, 48, 36, 24, 18, 12, 9, 6 Mbps				
802.11g Data Rates supported	54, 4	8, 36, 24, 18, 12,	11, 9, 6, 5.5, 2	, 1 Mbps	
802.11n Data Rates supported	270, 240, 180, 135, 130, 121.5, 120, 117, 108, 104, 90, 81, 7 65, 60, 58.5, 54, 52, 40.5, 39, 30, 27, 26, 19.5, 13.5, 13, 6. Mbps				
Encryption	WEP 64-bit and 128-bit, TKIP, AES-CCMP 128-bit				
Operating temperature	0°C −70°C				
Operating humidity	Max Operating Humidity 85 %				
Operating System Driver Support	Microsoft Client XP/Vista/Win 7 (32bit/64bit)				

COMMUNICATIONS - SERIAL / PARALLEL PORT PCIE ADD-IN CARD

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

SERIAL / PARALLEL PORT PCIE ADD-IN CARD	MT	DT	SFF	USFF		
Connector Type	RS-232 and IEEE1284					
Data Rates supported	50bps ~115.2Kbps (Serial) &Maximum 1.8MBp(Parallel)					
Controller Details						
Controller bus architecture (example PCIe 1.0a x1)	PCI Express one lane (x1)					
Driver Support	Microsoft Client XP/Vista/ Win 7 (32bit/64bit) Linux DOS					
Full height Serial / Parallel add-in card	Optional					
Environment						
Operation Temperature	0°C to 60°C (32°F to 140°F)					
Operation Humidity	5 to 95% RH					
Storage Temperature		-20°C to 85°C (-4°F to 185°F)			

COMMUNICATIONS - SERIAL PORT PCIE ADD-IN CARD

SERIAL PORT PCIE ADD-IN CARD	МТ	DT	SFF	USFF	
Connector Type	RS-232				
Data Rates supported	50bps ~115.2Kbps				
Controller Details					
Controller bus architecture (example PCIe 1.0a x1)	PCI Express one lane (x1)				
Driver Support	Microsoft Client XP/Vista/Win 7 (32bit/64bit) Linux DOS				
Half height Serial add-in card	Optional				
Environment					
Operation Temperature	0°C to 60°C (32°F to 140°F)				
Operation Humidity	5 to 95% RH				
Storage Temperature		-20°C to 85°	C (-4°F to 185	°F)	

COMMUNICATIONS - SERIAL / PARALLEL PORT PCIE ADD-IN CARD

PARALLEL PORT PCIE ADD-IN CARD	MT	DT	SFF	USFF		
Connector Type	IEEE1284					
Data Rates supported	Maximum 1.8MBp					
Controller Details						
Controller bus architecture (example PCIe 1.0a x1)	PCI Express one lane (x1)					
Driver Support	Microsoft Client XP/Vista/7 (32bit/64bit) Linux DOS					
Half height parallel add-in card		Optic	onal			
Environment						
Operation Temperature	0°C to 60°C (32°F to 140°F)					
Operation Humidity	5 to 95% RH					
Storage Temperature		-20°C to 85°C (-4°F to 185°F)			

GRAPHICS/VIDEO CONTROLLER

Onboard Graphics ^{1,2,3,4} Integrated Intel® HD Graphics 2500/4000 (3 rd generation Core i3/i5/i7 CPUs); Integrated Intel® HD Graphics 2000/3000 (2 nd generation Core i3 CPUs); Integrated Intel® HD Graphics (Pentium® Dual Core CPU);	МТ	DT	SFF	USFF		
Bus Type		Inte	egrated			
GPU core clock	Gen6 Core Intel® HD Graphics /HD Graphics 2000 @ 850MHz Gen7 Core Intel® HD Graphics 2500 / 4000 @ 650MHz					
Frame Buffer Memory (onboard and shared) Size and Speed			e system memo B system Memo			
Overlay Planes			Yes			
Maximum Color Depth	32 bit					
Maximum Vertical Refresh Rate	75 Hz					
Multiple Display Support			Yes			
Operating Systems Graphics/ Video API Support	OpenGL 3.1/OpenCLv1.1 /DirectX 11					
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	Up to 2560x1600 @ 60Hz (DP) Up to 1920x1200 @ 60Hz (VGA only)					
External Connectors	VGA, 2 DisplayPort					
<u>DisplayPort</u>						
Bus Type	DDPC					
DisplayPort Audio Support	Yes					
VGA						
Bus Type	CRT					
VGA Audio Support			No			

¹Up to 1.7 GB of system memory may be allocated to support integrated graphics, depending on operating system, system memory size and other factors

² 3rd generation CPUs natively support 3 displays with the integrated CPU graphics. Three simultaneous display output requires one DP port with a maximum resolution of 2500x1600 at 60Hz refresh rate and a DP and VGA port with max resolutions of 1920x1200 at 60Hz refresh rates.

³ Display output from both onboard and discrete simultaneously if multi display option in BIOS is enabled and OS used is Win7.

⁴ For dual graphics card configuration in PClex16 and PClex16 (wire as 4), Bios will disable multi display option automatically and display output only from graphics cards.

1GB AMD RADEON™ HD7570	МТ	DT	SFF	
Bus Type (example integrated or PCIe x16)	PCIEx16			
GPU core clock	650Mhz			
Frame Buffer Memory (onboard and shared) Size and Speed	800Mhz			
Maximum power consumption	50W			
Overlay Planes	Yes			
Maximum Color Depth		32-bit		
Maximum Vertical Refresh Rate		200Hz		
Multiple Display Support		Yes		
Operating Systems Graphics/ Video API Support	D3D/O	D3D/OpenGL 3.1/OpenCLv1.1/DirectX11		
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)		Dual-Link DVI: 2560 x 1600, 32-bit color DisplayPort: 2560 x 1600, 32-bit color		
External connectors		DisplayPort, DVI-I		
Dimensions of full height card inches/centimeters (L x H)	6.6 x 4.7 / 16.764 x 12.0			
Dimensions of low profile card inches/centimeters (L x H)		6.6 x 3.35 /	16.764 x 8.5	
Environmental Operating Conditions (Non-Condensing):				
Operating Temperature Range		10°C -55°C		
Relative Humidity Range		5-90% RH		
Altitude Range		0-20,000 ft.		
1GB AMD RADEON™ HD7470	МТ	DT	SFF	
Bus Type (example integrated or PCIe x16)		PCIEx16		
	775Mhz			
GPU core clock		775Mhz		
GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed		775Mhz 900Mhz		
Frame Buffer Memory (onboard and shared) Size and Speed		900Mhz		
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption		900Mhz 25W		
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes		900Mhz 25W Yes		
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth		900Mhz 25W Yes 32-bit		
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate	D3D/O	900Mhz 25W Yes 32-bit 200Hz	1/DirectX11	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support	Dual-Li	900Mhz 25W Yes 32-bit 200Hz Yes	32-bit color	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support	Dual-Li	900Mhz 25W Yes 32-bit 200Hz Yes penGL 3.1/OpenCLv1.	32-bit color 2-bit color	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	Dual-Li	900Mhz 25W Yes 32-bit 200Hz Yes penGL 3.1/OpenCLv1. nk DVI: 2560 x 1600, 320	32-bit color 2-bit color	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors	Dual-Li Displa 6.6 x 4.7 /	900Mhz 25W Yes 32-bit 200Hz Yes penGL 3.1/OpenCLv1. nk DVI: 2560 x 1600, 320	32-bit color 2-bit color	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Dimensions of full height card inches/centimeters (L x H)	Dual-Li Displa 6.6 x 4.7 /	900Mhz 25W Yes 32-bit 200Hz Yes penGL 3.1/OpenCLv1. nk DVI: 2560 x 1600, 32 pyPort: 2560 x 1600, 32	32-bit color 2-bit color	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Dimensions of full height card inches/centimeters (L x H) Dimensions of low profile card inches/centimeters (L x H)	Dual-Li Displa 6.6 x 4.7 /	900Mhz 25W Yes 32-bit 200Hz Yes penGL 3.1/OpenCLv1. nk DVI: 2560 x 1600, 32 pyPort: 2560 x 1600, 32	32-bit color 2-bit color	
Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Dimensions of full height card inches/centimeters (L x H) Dimensions of low profile card inches/centimeters (L x H) Environmental Operating Conditions (Non-Condensing):	Dual-Li Displa 6.6 x 4.7 /	900Mhz 25W Yes 32-bit 200Hz Yes penGL 3.1/OpenCLv1. nk DVI: 2560 x 1600, 3 pyPort: 2560 x 1600, 3 DisplayPort, DVI-I	32-bit color 2-bit color	

HARD DRIVES1

3.5" 1TB SATA 7200 RPM HDD		
Capacity	1TB	
Dimensions inches (W x D x H)	Approximately (4.00 x 5.787 x 1.028 inches)	
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0)	
Internal buffer size	32 MB	
Rotational Speed	7200 rpm	
Logical Blocks	1,953,525,168	
Power Source		
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)	
Spin Up Current (reference only)	5V (1A) ,12V (2A)	
Environmental Operating Conditions (Non-Condensing):		
Femperature Range 5°C to 60°C		
Relative Humidity Range	20% to 80% non-condensing	
Maximum Wet Bulb Temperature	29°C	
Altitude Range	-50 ft to 10000 ft	
Environmental Non-Operating Conditions (Non-Condensing):		
Temperature Range	-40°C to 65°C	
Relative Humidity Range	10% to 90% non-condensing	
Maximum Wet Bulb Temperature	38°C	
Altitude Range	-50 ft to 35000 ft	

 $^{^{1}}$ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

HARD DRIVES¹ (CONT.)

3.5" 500GB SATA 7200 RPM HDD			
Capacity	500GB		
Dimensions inches (W x D x H)	Approximately (4.00 x 5.787 x 1.028 inches)		
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0)		
Internal buffer size	16 MB		
Rotational Speed	7200 rpm		
Logical Blocks	976,773,168		
Power Source			
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)		
Spin Up Current (reference only)	5V (1A) ,12V (2A)		
Environmental Operating Conditions (Non-Condensing):			
Temperature Range	5°C to 60°C		
Relative Humidity Range	20% to 80% non-condensing		
Maximum Wet Bulb Temperature	29°C		
Altitude Range	-50 ft to 10000 ft		
Environmental Non-Operating Conditions (Non-Condensing):			
Temperature Range	-40°C to 65°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	38°C		
Altitude Range	-50 ft to 35000 ft		

¹ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

3.5" 250GB SATA 7200 RPM HDD			
Capacity	250GB		
Dimensions inches (W x D x H)	Approximately (4.00 x 5.787 x 1.028 inches)		
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0)		
Internal buffer size	8 MB		
Rotational Speed	7200 rpm		
Logical Blocks	488,397,168		
Power Source			
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)		
Spin Up Current (reference only)	5V (1A) ,12V (2A)		

Environmental Operating Conditions (Non-Condensing):			
Temperature Range	5°C to 60°C		
Relative Humidity Range	20% to 80% non-condensing		
Maximum Wet Bulb Temperature	29°C		
Altitude Range	-50 ft to 10000 ft		
Environmental Non-Operating Conditions (Non-Condensing):			
Temperature Range	-40°C to 65°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	38°C		
Altitude Range	-50 ft to 35000 ft		

 $^{^{1}}$ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

2.5" 500GB SATA 7200 RPM HDD			
Capacity	500GB		
Dimensions inches (W x D x H)	Approximately (3.93 x 2.75 x 0.374 inches)		
Interface type and Maximum speed	Up to 3Gb/s		
Internal buffer size	16 MB		
Rotational Speed	7200 rpm		
Logical Blocks	976,773,168		
Power Source			
Power Consumption (reference only)	Idle 0.7W, Active 3.25W		
Spin Up Current (reference only)	5V (1A)		
Environmental Operating Conditions (Non-Condensing):			
Temperature Range 5°C to 60°C			
Relative Humidity Range	20% to 80% non-condensing		
Maximum Wet Bulb Temperature	29°C		
Altitude Range	-50 ft to 10000 ft		
Environmental Non-Operating Conditions (Non-Condensing):			
Temperature Range	-40°C to 65°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	38°C		
Altitude Range	-50 ft to 35000 ft		

¹ For hard drives, GB means 1 billion bytes ; actual capacity varies with preloaded material and operating environment and will be less.

2.5" 320GB SATA 7200 RPM HDD			
Capacity	320GB		
Dimensions inches (W x D x H)	Approximately (3.93 x 2.75 x 0.374 inches)		
Interface type and Maximum speed	Up to 3Gb/s		
Internal buffer size	16 MB		
Rotational Speed	7200 rpm		
Logical Blocks	625, 142,448		
Power Source			
Power Consumption (reference only)	Idle 0.7W, Active 3.25W		
Spin Up Current (reference only)	5V (1A)		
Environmental Operating Conditions (Non-Condensing):			
Temperature Range	5°C to 60°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	29°C		
Altitude Range	-50 ft to 10000 ft		
Environmental Non-Operating Conditions (Non-Condensing):			
Temperature Range	-40°C to 65°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	38°C		
Altitude Range	-50 ft to 35000 ft		

¹ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

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2.5" 320GB SATA 7200 RPM OPAL SED W/FIPS HDD			
Capacity	320GB		
Dimensions inches (W x D x H)	Approximately (2.75 x 3.94 x 0.374 inches)		
Interface type and Maximum speed	Up to 3Gb/s		
Internal buffer size	16 MB		
Rotational Speed	7200 rpm		
Logical Blocks	625,142,448		
Power Source			
Power Consumption (reference only)	Idle 0.7W, Active 3.25W		
Spin Up Current (reference only)	5V (1A)		
Environmental Operating Conditions (Non-Condensing):			
Temperature Range	5°C to 60°C		
Relative Humidity Range	20% to 80% non-condensing		
Maximum Wet Bulb Temperature	29°C		
Altitude Range	-50 ft to 10000 ft		
Environmental Non-Operating Conditions (Non-Condensing	y):		
Temperature Range	-40°C to 65°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	38°C		
	-50 ft to 35000 ft		

¹ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

HARD DRIVES¹ (CONT.)

2.5" 500GB SATA 7200 RPMHYBRID HDD			
Capacity	500GB		
Dimensions inches (W x D x H)	Approximately (3.93 x 2.75 x 0.374 inches)		
Interface type and Maximum speed	Up to 6Gb/s		
Internal buffer size	16 MB		
Flash Cache	8GB		
Logical Blocks	976,773,168		
Power Source			
Power Consumption (reference only)	Idle 0.8W, Active 3.25W		
Spin Up Current (reference only)	5V (1A)		
Environmental Operating Conditions (Non-Condensing):			
Temperature Range	5°C to 60°C		
Relative Humidity Range	20% to 80% non-condensing		
Maximum Wet Bulb Temperature	29°C		
Altitude Range	-50 ft to 10000 ft		
Environmental Non-Operating Conditions (Non-Condensing):			
Temperature Range	-40°C to 65°C		
Relative Humidity Range	10% to 90% non-condensing		
Maximum Wet Bulb Temperature	38°C		
Altitude Range	-50 ft to 35000 ft		

¹ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

HARD DRIVES¹ (CONT.)

2.5" 128GB¹ SATA SOLID STATE DRIVE			
Capacity	128GB		
Dimensions inches (W x D x H)	Approximately (2.75 x 3.94 x 0.276 inches)		
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0)		
MTBF	1M hours		
Logical Blocks	250,069,680		
Power Source			
Power Consumption (reference only)	Idle 0.5W, Active 2.5W		

Environmental Operating Conditions (Non-Condensing):			
Temperature Range 0°C to 70°C			
Relative Humidity Range 10 to 90%			
Maximum Wet Bulb Temperature	ture 29°C		
Op Shock (@0.5ms)	1,500G		
Environmental Non-Operating Conditions (Non-Condensing):			
Temperature Range	-55°C to 95°C		
Relative Humidity Range	5 to 95%		
Maximum Wet Bulb Temperature 38°C			

¹ For hard drives, GB means 1 billion bytes ; actual capacity varies with preloaded material and operating environment and will be less.

OPTICAL DRIVES

DVD +/- RW ¹	MT	DT	SFF	USFF
External Dimensions inches/centimeters (Without Bezel – W x H x D)	148.2mm(6in)/42mm (2in)/ 171 (max)	148.2mm(6in)/42mm (2in)/ 171 (max)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)
Weight (max) pounds/ kilograms	700g	700g	170g	170g
Interface type and speed	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s
Disc Capacity	Standard	Standard	Standard	Standard
Internal buffer size	supplier dependent	supplier dependent	supplier dependent	supplier dependent
Access Times (typical)	supplier dependent	supplier dependent	supplier dependent	supplier dependent
Maximum Data Transfer Ra	tes			
Writes	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD	8x DVD / 24x CD
Reads	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD	8x DVD/ 24x CD
Power Source				
DC Power Requirements	12V, 5V	12V, 5V	5V	5V
DC Current	1200mA (12V)/ 900mA (5V)	1200mA (12V)/ 900mA (5V)	1000mA	1000mA
	Conditions (Non-Condensing)	:		
Operating Temperature Range	5°C to 50°C	5°C to 50°C	5°C to 50°C	5°C to 50°C
Relative Humidity Range	20% to 80% RH	20% to 80% RH	20% to 80% RH	20% to 80% RH
Maximum Wet Bulb Tem- perature	29°C	29°C	29°C	29°C
Altitude Range	-200 to 3048	-200 to 3048	-200 to 3048	-200 to 3048
Environmental Non-Operating Conditions (Non-Condensing):				
Operating Temperature Range	-40°C to 65°C	-40°C to 65°C	-40°C to 65°C	-40°C to 65°C
Relative Humidity Range	5% to 95% RH	5% to 95% RH	5% to 95% RH	5% to 95% RH
Maximum Wet Bulb Tem- perature	38°C	38°C	38°C	38°C
Altitude Range	-200 to 10600m	-200 to 10600m	-200 to 10600m	-200 to 10600m

¹ Discs burned with this drive may not be compatible with some existing drives and players; using DVD+R media provides maximum compatibility.

DVD-ROM	MT	DT	SFF	USFF	
External Dimensions inches/centimeters (Without Bezel – W x H x D)	148.2mm(6in)/42mm (2in)/ 171 (max)	148.2mm(6in)/42mm (2in)/ 171 (max)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)	
Weight (max) pounds/ kilograms	700g	700g	165g	165g	
Interface type and speed	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s	
Disc Capacity	Standard	Standard	Standard	Standard	
Internal buffer size	supplier dependent	supplier dependent	supplier dependent	supplier dependent	
Access Times (typical)	supplier dependent	supplier dependent	supplier dependent	supplier dependent	
Maximum Data Transfer Rates					
Writes	N/A	N/A	N/A	N/A	
Reads	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD	8x DVD/ 24x CD	

OPTICAL DRIVES (CONT.)

DVD-ROM (CONT.)	МТ	DT	SFF	USFF				
Power Source								
DC Power Requirements	12V, 5V	12V, 5V	5V	5V				
DC Current	1200mA (12V)/ 900mA (5V)	1200mA (12V)/ 900mA (5V)	800mA	800mA				
Environmental Operating C	Conditions (Non-Condensing)	:						
Operating Temperature Range	5°C to 50°C	5°C to 50°C	5°C to 50°C	5°C to 50°C				
Relative Humidity Range	20% to 80% RH	20% to 80% RH	20% to 80% RH	20% to 80% RH				
Maximum Wet Bulb Tem- perature	29℃	29℃	29℃	29°C				
Altitude Range	-200 to 3048m	-200 to 3048m	-200 to 3048m	-200 to 3048m				
Environmental Non-Operat	ting Conditions (Non-Conder	nsing):						
Operating Temperature Range	-40°C to 65°C	-40°C to 65°C	-40°C to 65°C	-40°C to 65°C				
Relative Humidity Range	5% to 95% RH	5% to 95% RH	5% to 95% RH	5% to 95% RH				
Maximum Wet Bulb Tem- perature	38°C	38°C	38°C	38°C				
Altitude Range	-200 to 10600m	-200 to 10600m	-200 to 10600m	-200 to 10600m				

MEDIA CARD READER (MCR)

NOTE: Dell 19 in 1 Media Card Reader (MCR) is supported via a F5 to F3 bay converter on the MT and DT and may require a slim line optical drive depending on selectable configuration. MCR is not available on the SFF and USFF chassis.

Weight (max) pounds/kilograms	19 IN 1 MEDIA CARD READER	MT/DT
Interface type and speed Media Supported (maximum capacity supported will vary by Flash Media Types) CF I CF II Micro Drive (MD) Secure Digital (SD) SDHC Micro Secure Digital (SD) SDHC Micro Solivith adapter) Multi Media Card (IMMC) RS Multi Media Card plus (IMMC plus) RS Multi Media Card Micro (IMMC Micro) (MS Pro Duo) Memory Stick Pro (MS Pro) Memory Stick Pro (MS Pro) Memory Stick Micro (IMMC Micro) (MS Pro Duo) Memory Stick Micr	External Dimensions inches/(centimeters) (With Bezel – W x H)	3.99/(10.13cm)/1.0/(2.54cm)
Media Supported (maximum capacity supported will vary by Flash Media Types) CF I CF II Micro Drive (MD) Secure Digital (SD) SDHC Min Secure Digital (SD) Micro Secure Digital (Imin-SD) Multi Media Card Micro-MMC plus) RS Multi Media Card plus (IMMC) plus) RS Multi Media Card plus (IMMC) plus) Remory Stick (Imin-Micro) (Im	Weight (max) pounds/kilograms	~155g
CF I CF II Micro Drive (MD) Secure Digital (SD) SDHC Mini Secure Digital (mini-SD) Micro Secure Digital (mini-SD) Multi Media Card (MMC) RS Multi Media Card (MMC) RS Multi Media Card plus (MMC plus) RS Multi Media Card plus (MMC plus) RS Multi Media Card plus (MMC plus) Memory Stick Pmo (MS Pmo) Memory Stick Minion(MS) Multi Media Card (MMC) Specification 4.2 Memory Stick Minion(MS) Memory Stick Minion Memory Stick	Interface type and speed	USB 2.0, 480Mb/s
CFII Micro Drive (MD) Secure Digital (SD) SDI-C	Media Supported (maximum capacity supported will vary by	Flash Media Types)
Support Specification Versions: Support Specification Versions: Support Specification Versions: Support Specification Versions: Secure Digital (SD) 2.0 Memory Stick Pro (MS-PRO) Specification 1.02 Memory Stick (MS) Specification 1.43 xD Specification 1.2 Power Source Max Power Requirements 2.5W Supply Voltage Range 4.75V ~ 5.25V Power Consumption: Standby less than 0.5mA @ 5.0VDC Environmental Operating Conditions (Non-Condensing): Operating Temperature Range 5°C to 50°C Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Media Supported	CF II Micro Drive (MD) Secure Digital (SD) SDHC Mini Secure Digital (mini-SD) Micro Secure Digital (Micro-SD)(with adapter) Multi Media Card (MMC) RS Multi Media Card (RS-MMC) Multi Media Card plus (MMC plus) RS Multi Media Card plus (MMC plus) RS Multi Media Card plus (RS-MMC plus) Multi Media Card Micro (MMC Micro) (with adapter) Memory Stick (MS) Memory Stick Pro (MS Pro) Memory Stick Pro Duo (MS Pro Duo) Memory Stick Duo (MS-Duo) Memory Stick Micro (MS) (with adapter)
Max Power Requirements 2.5W Supply Voltage Range 4.75V ~ 5.25V Power Consumption: Standby less than 0.5mA @ 5.0VDC Environmental Operating Conditions (Non-Condensing): Operating Temperature Range 5°C to 50°C Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Support Specification Versions:	Smart Media (SM) Specification 2003 Multi Media Card (MMC) Specification 4.2 Secure Digital (SD) 2.0 Memory Stick Pro (MS-PRO) Specification 1.02 Memory Stick (MS) Specification 1.43
Supply Voltage Range 4.75V ~ 5.25V Power Consumption: Standby less than 0.5mA @ 5.0VDC Environmental Operating Conditions (Non-Condensing): Operating Temperature Range 5°C to 50°C Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Power Source	
Power Consumption: Environmental Operating Conditions (Non-Condensing): Operating Temperature Range Standby less than 0.5mA @ 5.0VDC For to 50°C Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Max Power Requirements	2.5W
Environmental Operating Conditions (Non-Condensing): Operating Temperature Range 5°C to 50°C Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Supply Voltage Range	4.75V ~ 5.25V
Operating Temperature Range 5°C to 50°C Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Power Consumption:	Standby less than 0.5mA @ 5.0VDC
Relative Humidity Range 10% to 90% RH Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Environmental Operating Conditions (Non-Condensing):	
Environmental Non-Operating Conditions (Non-Condensing): Operating Temperature Range -40°C to 65°C	Operating Temperature Range	5°C to 50°C
Operating Temperature Range -40°C to 65°C	Relative Humidity Range	10% to 90% RH
	Environmental Non-Operating Conditions (Non-Condensir	ıg):
Relative Humidity Range 5% to 95% RH	Operating Temperature Range	-40°C to 65°C
	Relative Humidity Range	5% to 95% RH

BIOS DEFAULTS

System Configuration	Integrated NIC:	Enable w/PXE
,	Serial Port:	COM1
	SATA Operation:	AHCI
	Drives:	Enable (SATA-0, SATA-1, SATA-2, SATA-3)
	SMART Reporting:	Disable
		Enable (Boot Support, Front USB Ports, Rear
	USB Configuration:	Dual USB Ports, Rear Quad USB Ports)
	Miscellaneous Devices:	Enable (PCI Slot)
Video	Multi-display:	Disable (For system with discrete graphics)
Security	Strong Password:	Disable
	Password Configuration:	4~32
	Password Bypass	Disable
	Password Changes:	Enable
	TPM Security:	Disable
	Computrace®:	Deactivate
	CPU XD Support:	Enable
	OROM Keyboard Access	Enable
	Admin Setup Lockout	Disable
		Disable (For system with Chassis Intrusion
	Chassis Intrusion	detection)
Performance	Multiple Core Support:	All
	Intel® SpeedStep™:	Enable
	C States Control:	Enable
	Intel TurboBoost	Enable
	HyperThread control:	Enable
	HDD Protection Support	Enable (For China market only)
Power Management	AC Recovery:	Power Off
	Auto On Time:	Disable
	Deep Sleep Control:	Disable
	Fan Control Override:	Disable
	USB Wake Support	Disable
	Wake on LAN/WLAN:	Disable
	Block sleep	Disable
POST Behavior	Numlock LED:	Enable
	Keyboard Errors:	Enable
	POST HotKeys:	Enable
Vistors limetics C	Vistoralization	Fueble
Virtualization Support	Virtualization:	Enable
	VT for Direct I/O:	Enable
	Trusted Direct I/O	Disable
Maintenance	Service Tag:	Set by the factory
Maniteriance	Asset Tag:	Optional User Entry
	SERR Message:	Enable

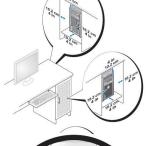
CHASSIS ENCLOSURE & VENTILATION REQUIREMENTS

ENCLOSURE VENTILATION

If your enclosure has doors, they need to be of a type that allows at least 30% airflow through the enclosure (front and back).

ENCLOSURE MINIMUM CLEARANCE

Leave a 10.2 cm (4 in.) minimum clearance on all vented sides of the computer to permit the airflow required for proper ventilation.



RECOMMENDED ENCLOSURE

Do not install your computer in an enclosure that does not allow airflow. This restricts the airflow and impacts your computer's performance, possibly causing it to overheat.



OPEN DESK MINIMUM CLEARANCE

If your computer is installed in a corner, on a desk, or under a desk, leave at least 5.1 cm (2 in.) clearance from the back of the computer to the wall to permit the airflow required for proper ventilation.



REGULATORY COMPLIANCE AND ENVIRONMENTAL

Product related conformity assessment and regulatory authorizations including Product Safety, Electromagnetic Compatibility (EMC), Ergonomics, and Communication Devices relevant to this product may be viewed at www.dell.com/regulatory_compliance. The Regulatory_Datasheet for this product is located at http://www.dell.com/regulatory_compliance.

Details of Dell's environmental stewardship program to conserve product energy consumption, reduce or eliminate materials for disposal, prolong product life span and provide effective and convenient equipment recovery solutions may be viewed at www.dell.com/environment. Product related conformity assessment, regulatory authorizations, and information encompassing Environmental, Energy Consumption, Noise Emissions, Product Materials Information, Packaging, Batteries, and Recycling relevant to this product may be viewed by clicking the Design for Environment link on the webpage.

OPTIPLEX 7010 MT

Component	Typical Configuration	High-end Configuration
CPU	Ivy Bridge i5 3470	Ivy Bridge i5 3770
Memory	4G DDR3 1600MHz	8G DDR3 1600MHz(x2)
HDD (#, capacity)	500G 7200RPM SATA3	1T 7200RPM SATA3(x2)
RMSD	16X DVD+/-RW SATA HH	16X DVD+/-RW SATA HH
Graphics Adapter	Intel® HD Graphics Family	ATI Radeon HD7570

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 7010 MT is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10^{-12} Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})
Idle	4.0	4.3
HDD Operating	4.0	4.4
90% CPU	4.0	4.8
ODD Operating	5.2	5.2

The Declared A-weighted Sound Pressure Level in decibels (re 2x10⁻⁵ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows¹:

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)		High-end Configuration Declared Sound Pressure (LpA)			id Pressure		
	Tab	е-Тор	Floor-S	Standing	Table	э-Тор	Floor- S	Standing
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	29.4	25.3	23.2	22.1	35.9	33.6	24.7	24.3
HDD Operating	29.5	25.7	23.6	22.2	36.9	34.7	25.4	24.5
90% CPU	30.3	26.9	23.9	22.7	37.5	35.9	26.9	26.8
ODD Operating	42.7	39.6	36.6	35.4	42.7	40.1	37.1	34.7

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

OPTIPLEX 7010 DT

Component	Typical Configuration	High-end Configuration
CPU	Ivy Bridge i5 3470	Ivy Bridge i5 3770
Memory	4G DDR3 1600MHz	8G DDR3 1600MHz(x2)
HDD (#, capacity)	500G 7200RPM SATA3	1T 7200RPM SATA3
RMSD	16X DVD+/-RW SATA HH	16X DVD+/-RW SATA HH
Graphics Adapter	Intel® HD Graphics Family	ATI Radeon HD7570

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 7010 DT is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})
Idle	3.4	3.9
HDD Operating	3.4	4.0
90% CPU	3.6	4.2
ODD Operating	5.1	5.2

The Declared A-weighted Sound Pressure Level in decibels (re 2x10⁻⁵ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows¹:

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)			High-end Configuration Declared Sound Press (LpA)			nd Pressure	
	Tabl	e-Top	Floor-S	Standing	Table	e-Top	Floor- S	Standing
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	22.5	20.1	19.8	19.1	25.2	23.1	22.0	21.1
HDD Operating	22.7	20.0	19.5	19.2	25.4	23.5	21.9	20.9
90% CPU	23.9	22.2	24.6	23.5	32.6	30.2	25.7	25.2
ODD Operating	44.5	39.3	36.3	35.1	44.5	39.5	37.2	35.4

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

OPTIPLEX 7010 SFF

Component	Typical Configuration	High-end Configuration
CPU	Ivy Bridge i5 3470	Ivy Bridge i5 3770
Memory	4G DDR3 1600MHz	8G DDR3 1600MHz(x2)
HDD (#, capacity)	500G 7200RPM SATA3	1T 7200RPM SATA3
RMSD	8X 12.7 SATA DVDRW	8X 12.7 SATA DVDRW
Graphics Adapter	Intel® HD Graphics Family	ATI Radeon HD7570

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 7010 SFF is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})
Idle	3.9	4.3
HDD Operating	3.9	4.3
90% CPU	3.9	4.4
ODD Operating	4.8	4.8

The Declared A-weighted Sound Pressure Level in decibels (re $2x10^{-5}$ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows¹:

Operating Mode	Typical Co	Typical Configuration Declared Sound Pressure (LpA)				High-end Configuration Declared Sound Pressure (LpA)			
	Table-Top		Floor-Standing		Table-Top		Floor- Standing		
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	
Idle	30.2	25.5	25.2	24.5	31.1	27.2	26.2	25.7	
HDD Operating	30.3	25.8	25.5	24.9	31.4	27.5	26.1	25.8	
90% CPU	33.1	29.2	26.9	26.0	34.3	30.7	28.9	28.5	
ODD Operating	36.5	32.7	30.9	29.9	37.7	32.9	32.9	32.1	

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

OPTIPLEX 7010 USFF

Component	Typical Configuration		
CPU	Ivy Bridge i5 3470		
Memory	4G DDR3 1600MHz		
HDD (#, capacity)	500G 7200RPM SATA2		
RMSD	8X 12.7 SATA DVDRW		
Graphics Adapter	Intel® HD Graphics Family		

The Declared Noise Emission in accordance with ISO 9296 for the Dell Optiplex 7010 USFF is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10^{-12} Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})		
Idle	3.9		
HDD Operating	3.9		
90% CPU	4.8		
ODD Operating	4.7		

The Declared A-weighted Sound Pressure Level in decibels (re $2x10^{-5}$ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows1:

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)					
	Table-Top		Floor-Standing			
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)		
Idle	28.5	25.4	22.9	21.6		
HDD Operating	28.6	25.6	22.9	21.7		
90% CPU	28.9	25.8	23.8	21.9		
ODD Operating	40.3	35.9	32.5	29.9		

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2